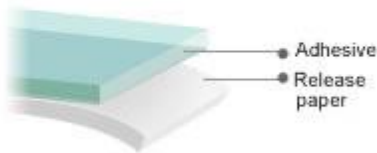


Thermal conductive adhesive transfer tape UT6520

Features

- Adhesive tape with lower environmental impact with UV curable manufacturing method (non solvent adhesive coating process).
- High thermal conductivity.
- High heat resistance; can be used in environments of up to 120°C.

Structure



Main component	Acrylic
Carrier	Non
Color	White
Adhesive thickness (μm)	About 200
Release paper thickness (μm)	About 150
Bonding strength (N/20mm) *	4.00
St'd size (width & length))	480mm × 50M

*90° Peeling strength /substrate : stainless steel SUS304 (surface is polished by #280 sandpaper)

Suitable use

- Can be used to fix the heat sink of LED backlight and LED illumination device.



Technical information

[Remarks]

*The above values are sample observed values, not the guaranteed performance.

1. Bonding strength on various type of substrate(90° peeling)

<Test piece condition>

Tape width : 20mm

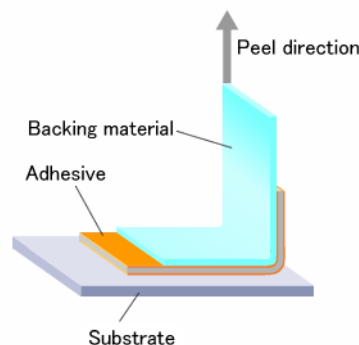
Bonding condition : One stroke with 2-kg roller

Measuring condition: 23°C ± 5°C 60% ± 20% RH

Peeling speed : 300mm/min

Backing material : 40μm Aluminum foil

[Left at RT for one hour before measurement]



< 90° Peeling strength test >

<Test data>

(N/20mm)

Substrate	Aluminum	Glass epoxy
90° Peeling strength	7	8

2. Holding power at different temperatures

<Test piece condition>

Substrate: Stainless steel plate (SUS304)

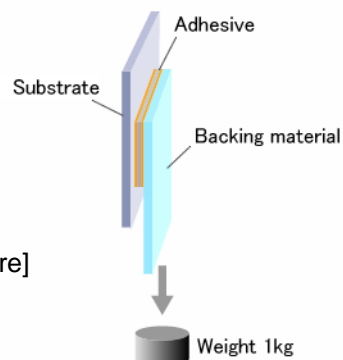
Bonding area : 25mmx25mm

Bonding condition : One stroke with 2-kg roller

Backing material : 40μm Aluminum foil

[Left at RT for one hour and then at each temperature for 30 minutes before measurement]

[Creep length after one hour application of 1-kg load at each temperature]



<Holding power test>

< Test data >

Measurement temperature	40°C	100°C
Creep length (mm)	0.2	0.2

3. Thermal conductivity : Measured by our self-made heat resistance meter

< Test piece condition >

Test piece size : 15mm × 15mm

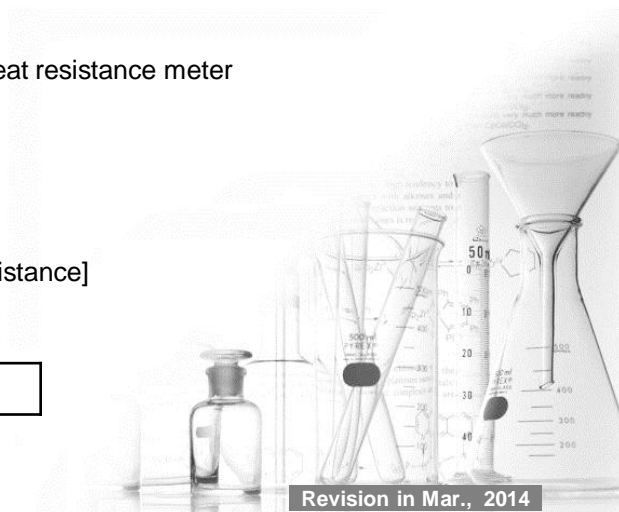
Setting electric power of heater : 10W

Pressure : 0.3MPa

[Left at RT for 30 minutes or more and measure heat resistance]

< Test data >

Thermal conductivity (W/(m·K))	1.0
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Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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